materials

MDPI

Supporting Information:

Polyether sulfone-based epoxy toughening: from micro- to nano-phase separation via PES end-chain modification and process engineering

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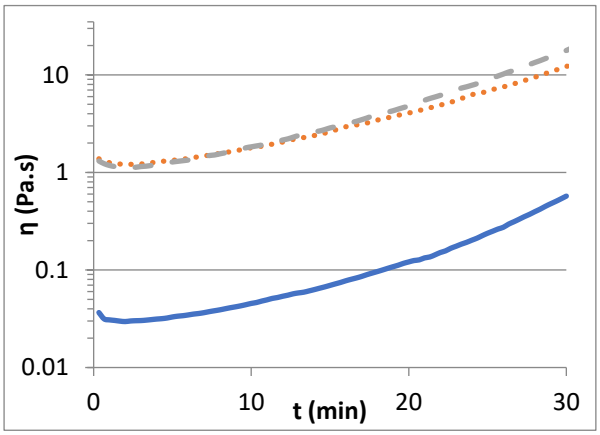

Figure S1. Evolution of the viscosity versus time for epoxy-amine-based systems cured under isothermal conditions. Full line: Neat system; dot line: f-PES system; dash line: nf-PES system.

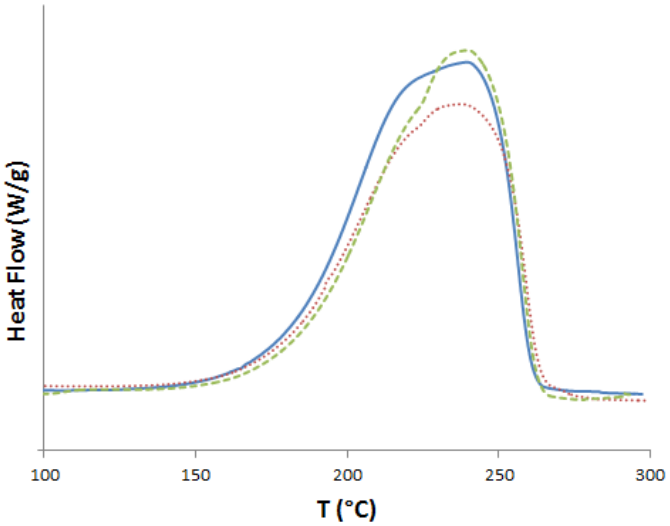

Figure S2. Enthalpy of reaction measured by DSC under dynamic curing conditions (10 °C/min) Blue: neat epoxy-amine system; Red: f-PES system; Green: nf-PES system.

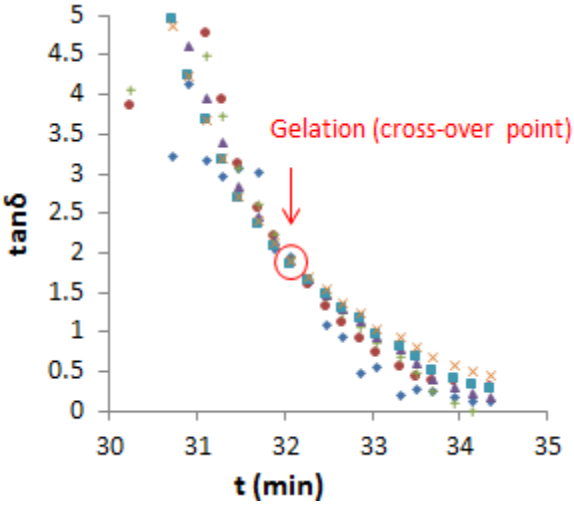

Figure S3. Variation of tan δ with reaction time for various frequencies (from 1Hz to 40 Hz) during isothermal curing at 150 °C for the neat epoxy-amine system.

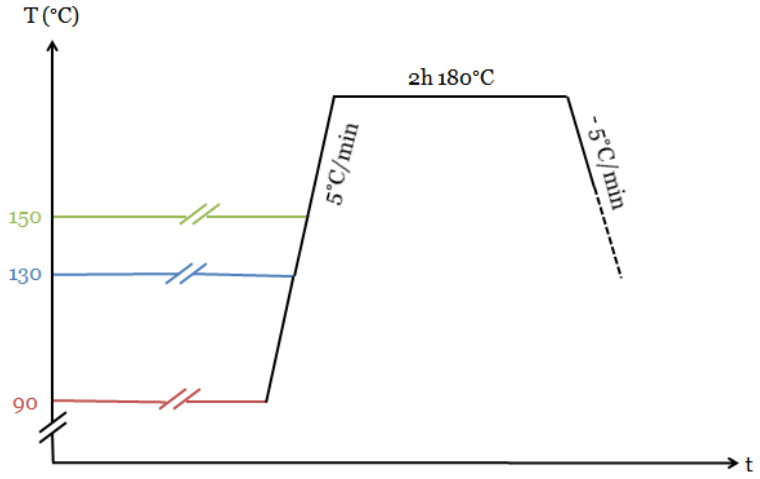

Figure S4. Scheme representation of the curing schedules considered in this study.

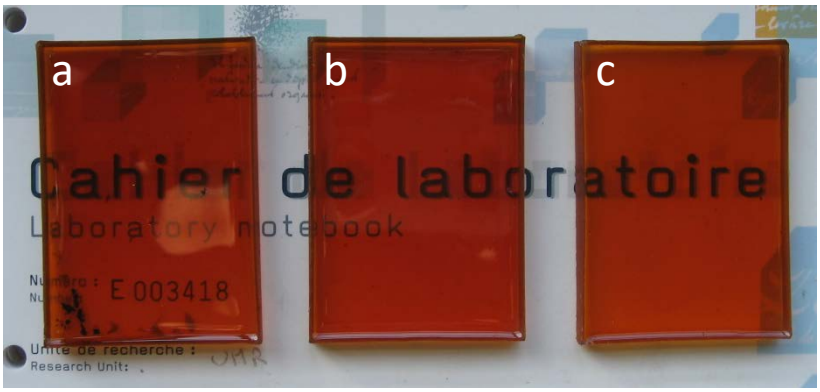

Figure S5. Visual aspect of the neat epoxy-amine network (**a**); the f-PES-based network (**b**) and the nf-PES-based network (**c**).

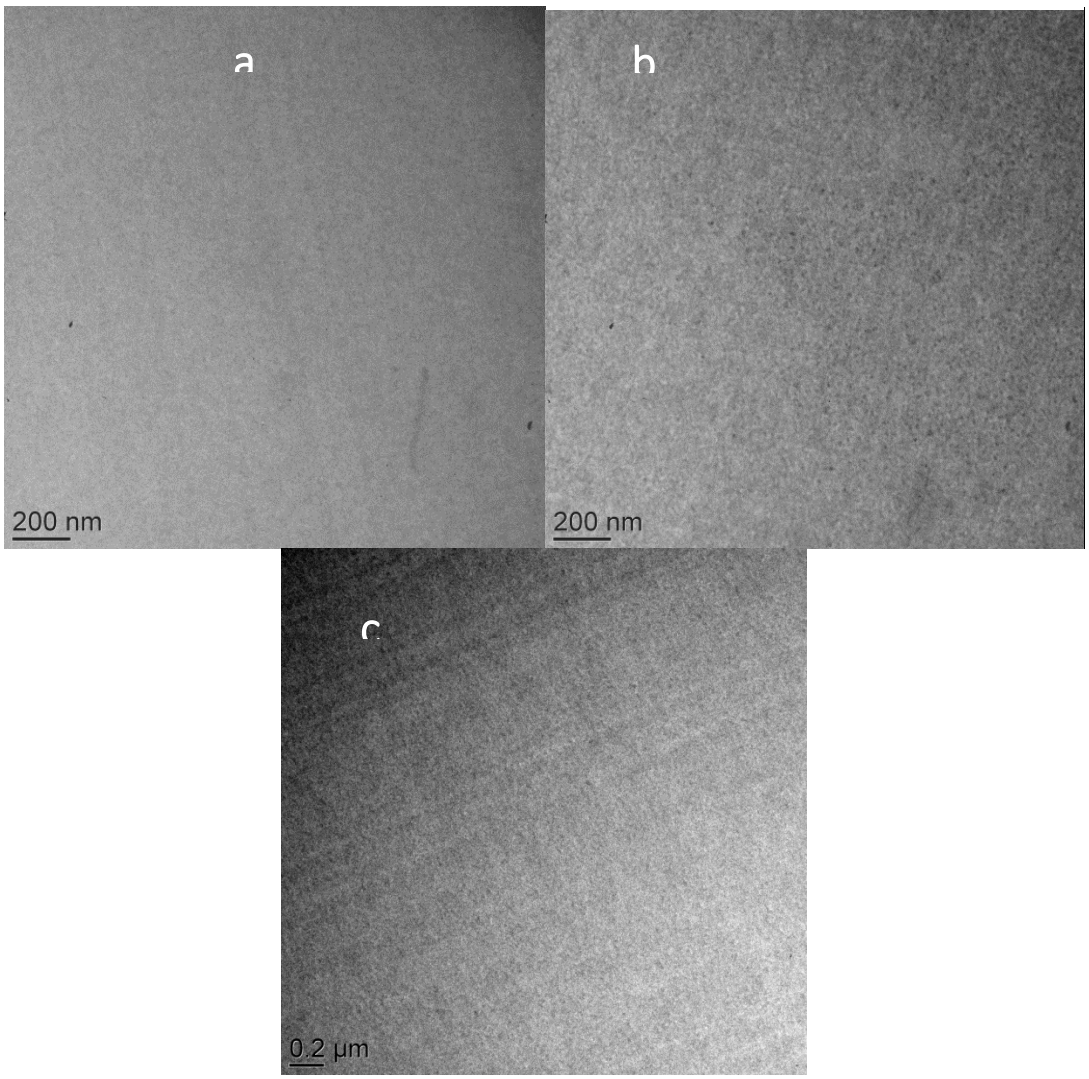

Figure S6. TEM micrographs of the neat epoxy-amine network (**a**); f-PES-based blend (**b**) and nf-PES-based blend (**c**) cured at 90 °C.